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(74) Agents: **STEFFEY, Charles E.** et al.; Schwegman, Lund-
berg, Woessner & Kluth, P.O. Box 2938, Minneapolis,
Minnesota 55402 (US).

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(71) Applicant (for all designated States except US): **INTEL
CORPORATION** [US/US]; 2200 Mission College Boul-
vard, Santa Clara, CA 95052 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **HENAO, Maria, V.**
[US/US]; 6161 Viado Los Cierros, Pleasanton, CA 94566
(US). **MU, Xiao-Chun** [US/US]; 19685 Via Escuela
Drive, Saratoga, CA 95070 (US). **MA, Qing** [US/US]; 919
Brentwood Drive, San Jose, CA 95129 (US). **VU, Quat,
T.** [US/US]; 2464 El Camino Real, Santa Clara, CA 95051
(US). **TOWLE, Steven, N.** [US/US]; 301 West Desert
Flower Lane, Phoenix, AZ 85045 (US).

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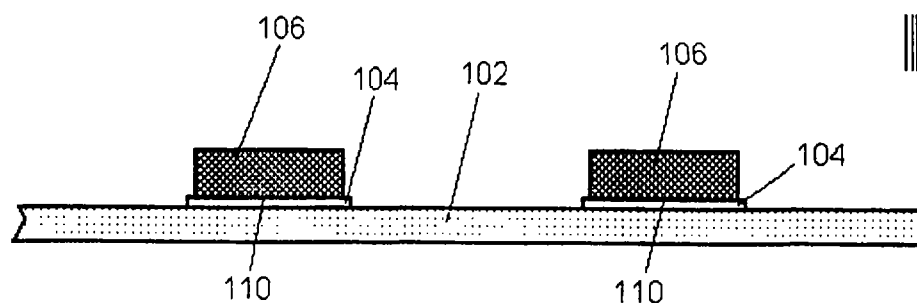
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(54) Title: MICROELECTRONIC PACKAGE HAVING AN INTEGRATED HEAT SINK AND BUILD-UP LAYERS



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(57) Abstract: A microelectronic package fabrication technology that attaches at least one microelectronic die onto a heat spreader and encapsulates the microelectronic die/dice thereon which may further include a microelectronic packaging core abutting the heat spreader wherein the microelectronic die/dice reside within at least one opening in a microelectronic package core. After encapsulation, build-up layers may be fabricated to form electrical connections with the microelectronic die/dice.

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